

## General Description

The AO4422 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

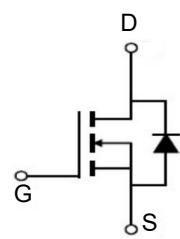
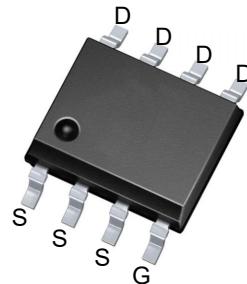


: YUh fYg

|                           |    |     |
|---------------------------|----|-----|
| $X_{FUU}$                 | 30 | X   |
| $I_F$                     | 12 | C   |
| $T_{FUQP+CVXI U? 10X_+}$  | 10 | o á |
| $T_{FUQP+CVXI U? 4.5X_+}$ | 12 | o á |

## Application

- Battery Protection
- Š[ æ Á, á&@
- Wj ä CII^] cæ|Á[ , ^|Á^] ]|^



## DUM\_U[ Y A Ur\_]b[ UbX CfXYf]b[ -bZfa U]cb

| DfcXi Wi-B | DUM_ | A Ur_]b[ | E lmfd7 Gz |
|------------|------|----------|------------|
| AO4422     | ÙUÚß | 4422     | HEEE       |

5 Vgc`i hÝAU] ja i a 'FU]b[ g'fH, 18) °C unless otherwise noted)

| Symbol                   | Parameter  | Rating     | Units |
|--------------------------|--|------------|-------|
| $V_{DS}$                 | Drain-Source Voltage                             | 30         | V     |
| $V_{GS}$                 | Gate-Source Voltage                              | $\pm 20$   | V     |
| $I_D @ T_A = 25^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^1$       | 12         | A     |
| $I_D @ T_A = 70^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^1$       | 8          | A     |
| $I_{DM}$                 | Pulsed Drain Current <sup>2</sup>                | 30         | A     |
| EAS                      | Single Pulse Avalanche Energy <sup>3</sup>       | 20         | mJ    |
| $I_{AS}$                 | Avalanche Current                                | 22         | A     |
| $P_D @ T_A = 25^\circ C$ | Total Power Dissipation <sup>4</sup>             | 4.5        | W     |
| $T_{STG}$                | Storage Temperature Range                        | -55 to 150 | °C    |
| $T_J$                    | Operating Junction Temperature Range             | -55 to 150 | °C    |
| $R_{\theta JA}$          | Thermal Resistance Junction-ambient <sup>1</sup> | 50         | °C/W  |
| $R_{\theta JC}$          | Thermal Resistance Junction-Case <sup>1</sup>    | 30         | °C/W  |

Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

| Symbol                                     | Parameter  | Conditions  | Min. | Typ.  | Max.      | Unit                       |
|--|--|---|------|-------|-----------|----------------------------|
| $\text{BV}_{\text{DSS}}$                   | Drain-Source Breakdown Voltage                     | $V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$  | 30   | ---   | ---       | V                          |
| $\Delta \text{BV}_{\text{DSS}}/\Delta T_J$ | BVDSS Temperature Coefficient                      | Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$  | ---  | 0.027 | ---       | $\text{V}/^\circ\text{C}$  |
| $R_{\text{DS}(\text{ON})}$                 | Static Drain-Source On-Resistance <sup>2</sup>     | $V_{\text{GS}}=10\text{V}$ , $I_D=8\text{A}$  | ---  | 10    | 12        | $\text{m}\Omega$           |
|  |  | $V_{\text{GS}}=4.5\text{V}$ , $I_D=6\text{A}$   | ---  | 12    | 15        |                            |
| $V_{\text{GS}(\text{th})}$                 | Gate Threshold Voltage                             |   | 0.5  | 1.5   | 2         | V                          |
| $\Delta V_{\text{GS}(\text{th})}$          | $V_{\text{GS}(\text{th})}$ Temperature Coefficient | $V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$  | ---  | -5.8  | ---       | $\text{mV}/^\circ\text{C}$ |
| $I_{\text{DS}}$                            | Drain-Source Leakage Current                       | $V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$                       | ---  | ---   | 1         | $\mu\text{A}$              |
|  |  | $V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$                       | ---  | ---   | 10        |                            |
| $I_{\text{GS}}$                            | Gate-Source Leakage Current                        | $V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$  | ---  | ---   | $\pm 100$ | nA                         |
| $g_{\text{fs}}$                            | Forward Transconductance                           | $V_{\text{DS}}=5\text{V}$ , $I_D=10\text{A}$  | ---  | 5.8   | ---       | S                          |
| $R_g$                                      | Gate Resistance                                    | $V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$                               | ---  | 2.2   | 3.8       |                            |
| $Q_g$                                      | Total Gate Charge (4.5V)                           | $V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_D=10\text{A}$                           | ---  | 12.6  | 17.6      | nC                         |
| $Q_{\text{gs}}$                            | Gate-Source Charge                                 |   | ---  | 4.2   | 5.9       |                            |
| $Q_{\text{gd}}$                            | Gate-Drain Charge                                  |   | ---  | 5.1   | 7.1       |                            |
| $T_{\text{d(on)}}$                         | Turn-On Delay Time                                 | $V_{\text{DD}}=15\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=3.3\text{k}\Omega$<br>$I_D=10\text{A}$ | ---  | 6.2   | 12.4      | ns                         |
| $T_r$                                      | Rise Time  |   | ---  | 59    | 106       |                            |
| $T_{\text{d(off)}}$                        | Turn-Off Delay Time                                |   | ---  | 27.6  | 55        |                            |
| $T_f$                                      | Fall Time  |   | ---  | 8.4   | 16.8      |                            |
| $C_{\text{iss}}$                           | Input Capacitance                                  | $V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$                              | ---  | 960   | ---       | pF                         |
| $C_{\text{oss}}$                           | Output Capacitance                                 |   | ---  | 139   | ---       |                            |
| $C_{\text{rss}}$                           | Reverse Transfer Capacitance                       |   | ---  | 87    | ---       |                            |
| $I_s$                                      | Continuous Source Current <sup>1,5</sup>           | $V_G=V_D=0\text{V}$ , Force Current   | ---  | ---   | 10.3      | A                          |
| $I_{\text{SM}}$                            | Pulsed Source Current <sup>2,5</sup>               |   | ---  | ---   | 42        | A                          |
| $V_{\text{SD}}$                            | Diode Forward Voltage <sup>2</sup>                 | $V_{\text{GS}}=0\text{V}$ , $I_S=1\text{A}$ , $T_J=25^\circ\text{C}$                                  | ---  | ---   | 1.2       | V                          |
| $t_{\text{rr}}$                            | Reverse Recovery Time                              | $ I =10\text{A}$ , $di/dt=100\text{A}/\mu\text{s}$ ,<br>$T_J=25^\circ\text{C}$                        | ---  | 12.5  | ---       | nS                         |
| $Q_{\text{rr}}$                            | Reverse Recovery Charge                            |   | ---  | 5     | ---       | nC                         |

Note :

- 1 .The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3 .The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $L=0.1\text{mH}$ , $I_{\text{AS}}=35\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature 5.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

### Typical Characteristics

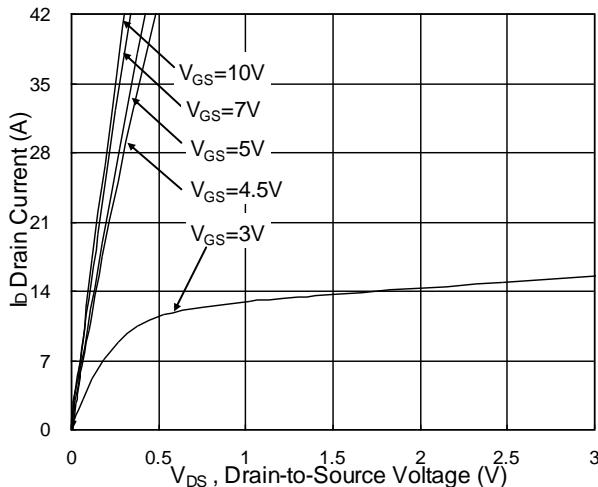


Fig.1 Typical Output Characteristics

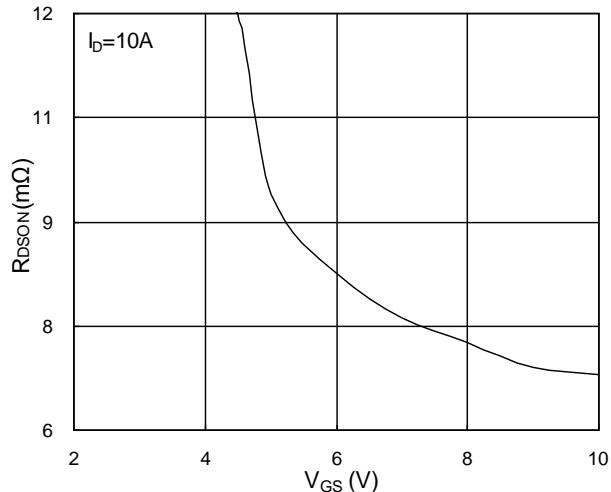


Fig.2 On-Resistance vs. Gate-Source

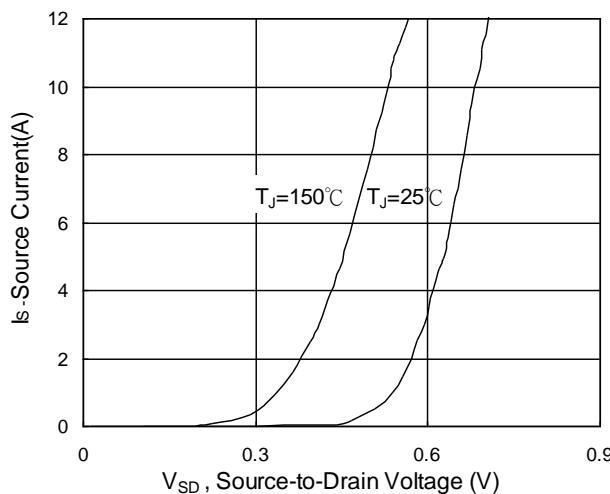


Fig.3 Forward Characteristics of reverse

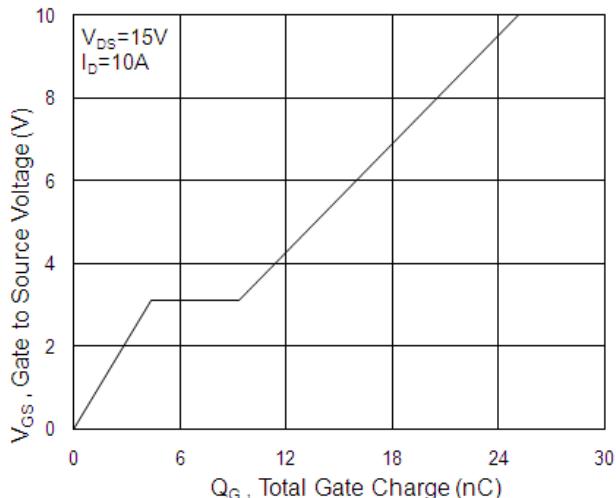
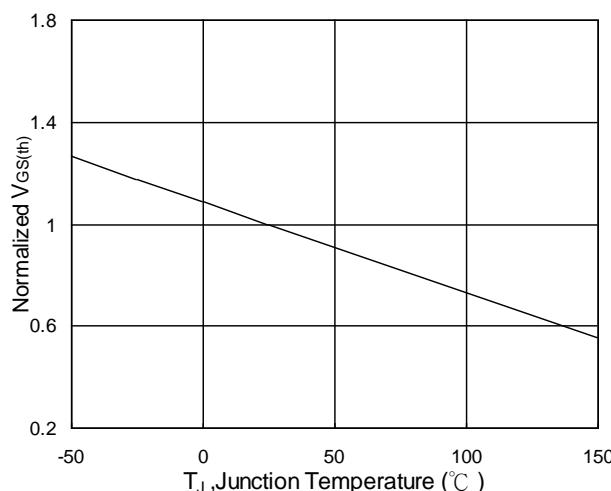
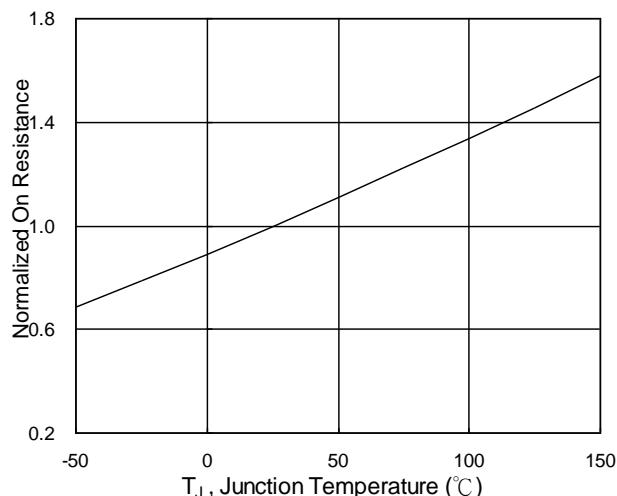


Fig.4 Gate-Charge Characteristics

Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$ Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

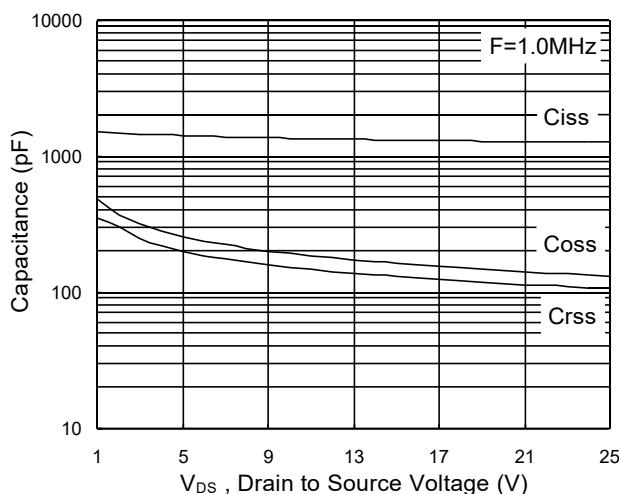


Fig.7 Capacitance

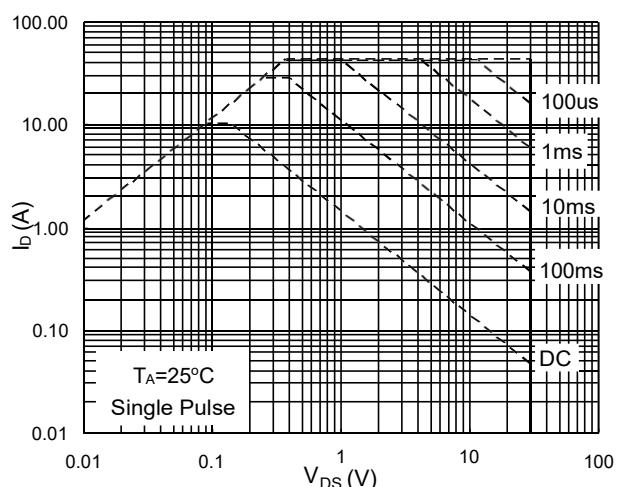


Fig.8 Safe Operating Area

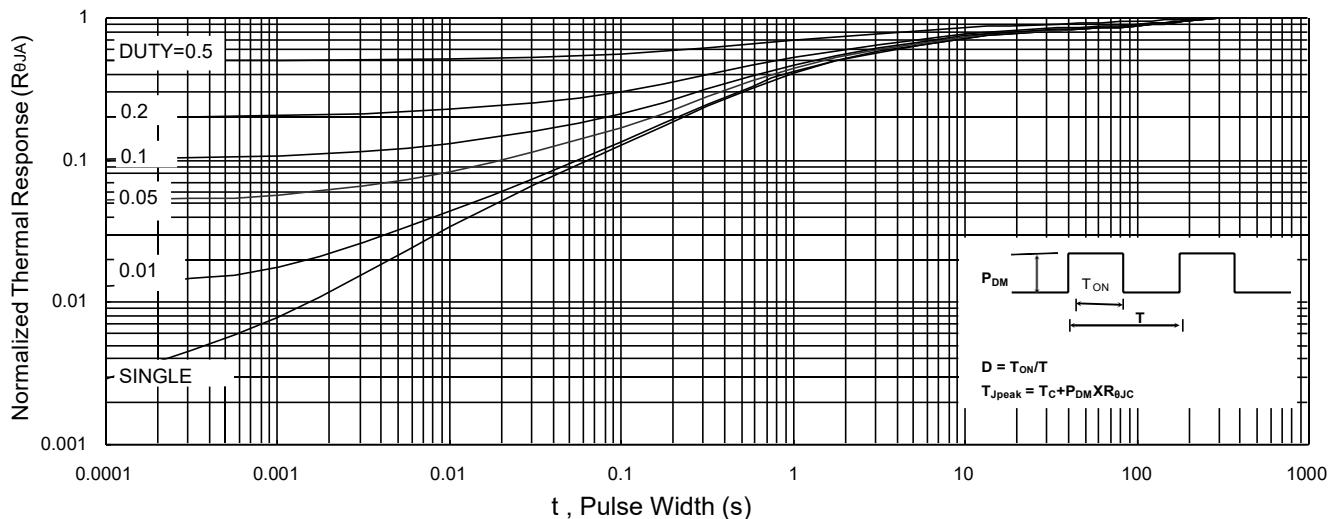


Fig.9 Normalized Maximum Transient Thermal Impedance

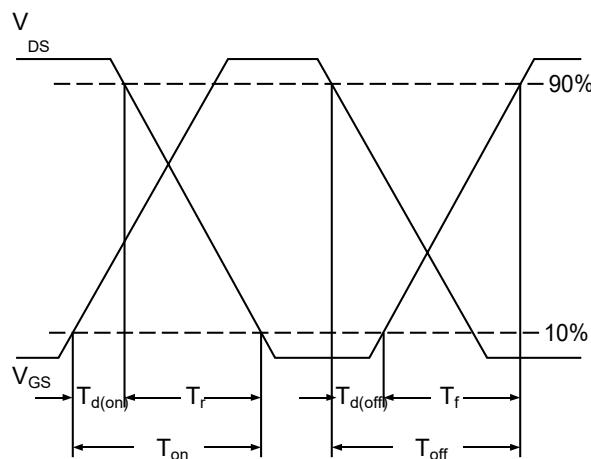


Fig.10 Switching Time Waveform

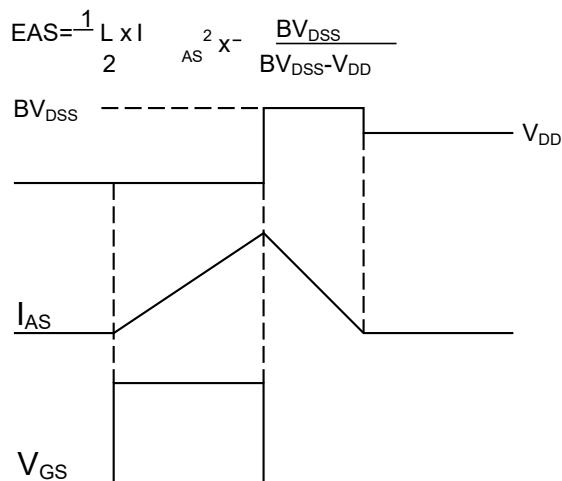
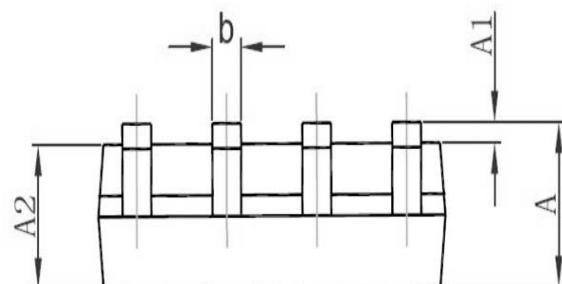
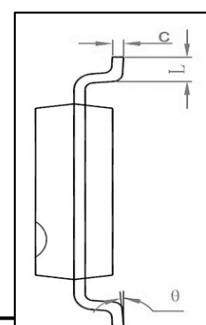
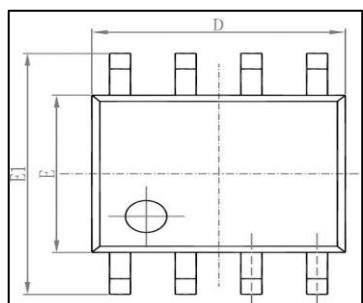


Fig.11 Unclamped Inductive Switching Waveform

## Package Mechanical Data-SOP-8



| Symbol | Dimensions in Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min                       | Max   | Min                  | Max   |
| A      | 1.350                     | 1.750 | 0.053                | 0.069 |
| A1     | 0.100                     | 0.250 | 0.004                | 0.010 |
| A2     | 1.350                     | 1.550 | 0.053                | 0.061 |
| b      | 0.330                     | 0.510 | 0.013                | 0.020 |
| c      | 0.170                     | 0.250 | 0.006                | 0.010 |
| D      | 4.700                     | 5.100 | 0.185                | 0.200 |
| E      | 3.800                     | 4.000 | 0.150                | 0.157 |
| E1     | 5.800                     | 6.200 | 0.228                | 0.244 |
| e      | 1.270 (BSC)               |       | 0.050 (BSC)          |       |
| L      | 0.400                     | 1.270 | 0.016                | 0.050 |
| θ      | 0°                        | 8°    | 0°                   | 8°    |

